Claims

[c1] An integrated circuit package device having a plurality of contact points, wherein the plurality of contact points of said at least one integrated circuit package device circuit board include an inner portion of contact points and an outer portion of said contact points, the integrated circuit package device comprising at least one of the following:
(i) one or more power supply contacts configured substantially in said outer portion of said integrated circuit package device;
(ii) one or more timing or frequency contacts substantially in said outer portion of said integrated circuit package device;
(iii) one or more ground contacts configured substantially in said inner portion of said integrated circuit package device; and
(iv) one or more data or high speed signal contacts configured substantially in said inner portion of said integrated circuit package device.

[c2] The integrated circuit package device according to Claim 1, wherein the ground contacts are further provided along a bisectional axis, through said outer portion of contacts to facilitate a ground path from outside an area of the integrated circuit to said inner portion.

[c3] The integrated circuit package device according to Claim 1, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

[c4] The integrated circuit package device according to Claim 1, wherein, for one or more of said signals associated with (i) to (iv), all of said respective contacts of said integrated circuit are configured in the respective manner described in one or more of (i) to (iv).

[c5] A printed circuit board having a plurality of tracks for operably coupling electrical signals to a plurality of contact points of at least one integrated circuit package device, wherein the plurality of contact points of said at least one integrated circuit package device circuit board include an inner portion of contact points and an outer portion of contact points, the printed circuit board comprising at least one of the following:

(i) one or more power supply contacts configured substantially in said outer portion of said integrated circuit package device;
(ii) one or more timing or frequency contacts substantially in said outer portion of said integrated circuit package device
(iii) one or more ground contacts configured substantially in said inner portion of said integrated circuit package device; and
(iv) one or more data or high speed signal contacts configured substantially in said inner portion of said integrated circuit package device.

[c6] The printed circuit board according to Claim 5, wherein the ground contacts are further provided along a bisectional axis, through said outer portion of contacts to facilitate a ground path from outside an area of the integrated circuit to said inner portion.

[c7] The printed circuit board according to Claim 5, wherein said inner portion is formed substantially of ground contact points to effect a ground plane.

[c8] The printed circuit board according to Claim 5, wherein, for one or more of said signals associated with (i) to (iv), all of said respective contacts of said integrated circuit are configured in the respective manner described in one or more of (i) to (iv).

[c9] An electrical or electronic device comprising the integrated circuit package device according to claim 5.